CHIP PEELING METHOD, CHIP PEELING APPARATUS AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD

Abstract

Provided is a chip-peeling method, a chip-peeling apparatus, and a method of manufacturing a semiconductor in which a part of a rim portion of a chip can be peeled by a large peeling force at an early stage of the peeling, and in which, at the time of sliding, the chip to be peeled can be easily peeled and taken out. A stage (16) is arranged immediately below an adhesive sheet (12) having an upper surface to which a chip (11) is attached. The stage (16) includes a fixed-stage portion (16b) and a movable-stage portion (16a). Under a state in which the chip (11) is supported by the movable-stage portion (16a), a part of a rim portion of the chip (11) is protruded from the movable-stage portion (16a). In a protruding state, a protruding portion of the chip (11) is trust up through intermediation of the adhesive sheet (12) with a projection-like portion (50), and then or at the same time, a negative pressure is brought into action in a void (19) in a lower portion of the protruding portion (31) and the movable-stage portion (16a) is driven.

FIG. 1A, FIG. 1B & FIG. 1C